

NOV 21 2005

PATENT

All v. DKL No. APPM/007094.P1/DSML/OW KJW

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:  
Yim, et al.**

Serial No.: 10/773,060

Confirmation No.: 5473

**Filed:** February 4, 2004

**For: Ultra Low Dielectric Materials  
Based on Hybrid System of Linear  
Silicon Precursor and Organic  
Porogen by Plasma-Enhanced  
Chemical Vapor Deposition  
(PECVD)**

MAIL STOP AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Group Art Unit: 1762

**Examiner: Marianne L. Padgett**

**CERTIFICATE OF FACSIMILE  
TRANSMISSION UNDER 37 CFR 1.8**

**SECOND RESPONSE TO FINAL OFFICE ACTION DATED AUGUST 26, 2005**

In response to the Final Office Action dated August 26, 2005, having a shortened statutory period for response set to expire on November 26, 2005, please enter this response and reconsider the claims pending in the application for reasons discussed below. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/007034.P1/KMT for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Amendments to the Claims are listed beginning on page 2 of this paper.**  
**Remarks begin on page 5 of this paper.**